Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	8 X 8 X 0.75 (6.6 EP)
Lead Count	56
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Non-Magnetic

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	9.17E-02	86.2	862000	45.86	458556
Thermosets	Epoxy resin	Proprietary	6.38E-03	6.0	60000	3.19	31918
Thermosets	Phenol resin	Proprietary	6.38E-03	6.0	60000	3.19	31918
Other inorganic materials	Metal Hydroxide	Proprietary	1.60E-03	1.5	15000	0.80	7980
Other inorganic materials	Carbon black	1333-86-4	3.19E-04	0.3	3000	0.16	1596
Subtotal			1.06E-01	100.00	1000000	53.20	531968

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.81 E-02	99.25	992500	39.05	390521
Copper & its alloys	Chromium	7439-89-6	2.36 E-04	0.30	3000	0.12	1180
Copper & its alloys	Tin	7440-66-6	1.97 E-04	0.25	2500	0.10	984
Copper & its alloys	Zinc	7723-14-0	1.57 E-04	0.20	2000	0.08	787
Subtotal			7.87 E-02	100.00	1000000	39.35	393472

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.24 E-04	100.0	1000000	0.16	1620

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.48 E-03	100.0	1000000	2.24	22399

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.06 E-03	100.0	1000000	1.53	15304

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.45 E-03	100.0	1000000	2.72	27241

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.06 E-03	66.34	663400	0.53	5305
Thermoset	Epoxy resin	Proprietary	8.97 E-05	5.61	56100	0.04	449
Other organic materials	Aliphatic acid anhydride	Proprietary	8.97 E-05	5.61	56100	0.04	449
Other organic materials	2,6 diglycidyl phenyl allyl ether oligomer	Proprietary	8.97 E-05	5.61	56100	0.04	449
Other organic materials	Epoxy derivative	Proprietary	8.97 E-05	5.61	56100	0.04	449
Other organic materials	1,4-bis(2,3-epoxypropoxy)butane	Proprietary	8.97 E-05	5.61	56100	0.04	449
Other organic materials	Hexahydromethylphthalic anhydride	Proprietary	8.97 E-05	5.61	56100	0.04	449
Subtotal			1.60 E-03	100.00	1000000	0.80	7996

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.00 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	LFCSP - Punched
Body Size (mm)	8 X 8 X 0.85 (6.5EP)
Lead Count	56
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.04E-02	86.9	869100	33.17	331684
Thermosets	Epoxy & Phenol Resin	Proprietary	1.03E-02	12.8	127800	4.88	48774
Other inorganic materials	Carbon black	1333-86-4	2.51E-04	0.3	3100	0.12	1183
Subtotal			8.10 E-02	100.00	1000000	38.16	381640

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.13 E-01	97.5	975000	53.10	530972
Copper & its alloys	Iron	7439-89-6	2.71 E-03	2.35	23500	1.28	12798
Copper & its alloys	Zinc	7440-66-6	1.39 E-04	0.12	1200	0.07	654
Copper & its alloys	Phosphorus	7723-14-0	3.47 E-05	0.03	300	0.02	163
Subtotal			1.16 E-01	100.00	1000000	54.46	544586

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.16 E-04	100.0	1000000	0.05	545

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.61 E-03	100.0	1000000	2.18	21751

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.37 E-03	100.0	1000000	0.65	6455

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	8.29 E-03	100.0	1000000	3.91	39079

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.27 E-04	73.54	735400	0.44	4370
Other organic materials	Epoxy resin A	TS ref# 10013	9.27 E-05	7.35	73500	0.04	437
Others	Anhydride	TS ref# 10181	9.27 E-05	7.35	73500	0.04	437
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.71 E-05	2.94	29400	0.02	175
Other organic materials	Epoxy resin B	TS ref# 10237	3.71 E-05	2.94	29400	0.02	175
Others	Epoxy resin modifier	TS ref# 10038	3.71 E-05	2.94	29400	0.02	175
Others	Anhydride	TS ref# 10180	3.71 E-05	2.94	29400	0.02	175
Subtotal			1.26 E-03	100.0	1000000	0.59	5943

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.12 E-01**	**100**	**1000000**

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ANALOG DEVICES